Soder-Wick® No Clean Desoldering Braid

Product Description

Soder-Wick No Clean is designed to provide fast and safe desoldering without leaving behind harmful flux residues. Soder-Wick No Clean uses pure, oxygen free copper braid and a patented flux technology to make an efficient and effective desoldering braid. Soder-Wick No Clean SD is available on ESD safe bobbins for protection against damage due to static electricity.

- Requires little or no post solder cleaning
- No corrosive residues
- Halide free
- ESD Safe bobbins meet specs:
  - MIL-STD-1686C
  - MIL-HDBK-263B
  - Static decay provision of MIL-B-81705C
- Minimal risk of heat and static component damage

Typical Applications

Soder-Wick No Clean safely removes solder from:

- Lugs and Posts
- Micro Circuits
- Surface Mount Device Pads
- Ball Grid Array Pads

Soder-Wick No Clean Meets or Exceeds:

- MIL-F-14256F, Type R
- DOD-STD-883E, Method 2022
- Bellcore TR-NWT-000078
- ANSI/IPC J SF-818

Typical Product Data and Physical Properties

Surface Insulation Resistance				
Bellcore TR-NWT-000078				**: PASS**
After 96 Hours (megohms) 2 x 10^4 Limit				
Group A	Group B	Group C		
4.8 x 10^6	3.8 x 10^6	4.1 x 10^6		
ANSI/IPC J SF-818				**: PASS**
After 168 Hours (ohms) 1.8 x 10^8 Limit				
1-2	2-3	3-4	4-5	
2.3 x 10^{10}	2.6 x 10^6	2.8 x 10^6	2.8 x 10^{10}	
Electromigration				**: PASS**
Average Insulation Resistance (megohms)-One Decade Limit				
	Initial	Final		
Group E	3.93 x 10^3	1.24 x 10^4		
Group F	3.87 x 10^3	2.84 x 10^4		
At 10x magnification no evidence of electomigration or heavy corrosion.				
Silver Chromate Test Paper	**PASS**			
Copper Mirror Test	**PASS**			
Shelg Life:	2 years			
RoHS Compliant	Yes			

Soder-Wick® No Clean Desoldering Braid

Usage Instructions

For industrial use only. Read SDS carefully prior to use.

1) Choose a Soder-Wick® No Clean width equal to or slightly larger than the pad or connection.
2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
3) Set temperature of iron between 600-750°F.
4) Place wick on solder joint and place tip of hot iron on top of wick.
5) As solder becomes molten, the color of the wick will change from copper to silver.
6) Remove wick and iron from joint simultaneously once color change has stopped.
7) The component lead / pad is now clean and free from solder.
8) Clip and discard used portion of the wick

Part #	Size Inches	Color	Size Metric
1	.030”	White	.76mm
2	.060”	Yellow	1.52mm
3	0.80”	Green	2.03mm
4	.110”	Blue	2.79mm
5	.145”	Brown	3.68mm
6	.210”	Red	5.33mm

Availability

Part #	Size	Length	Part#	Size	Length
60-1-5	1	5	60-1-10	1	10
60-2-5	2	5	60-2-10	2	10
60-3-5	3	5	60-3-10	3	10
60-4-5	4	5	60-4-10	4	10
60-5-5	5	5	60-5-10	5	10
60-6-5	6	5			

VacuPak™ Packaging

The VacuPak™ Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

Part #	Size
SW16025	2
SW16035	3
SW16045	4

Technical and Application Assistance

Chemtronics provides a technical hotline to answer your technical and application related questions.
The toll free number is: 1-800-TECH-401.

Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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